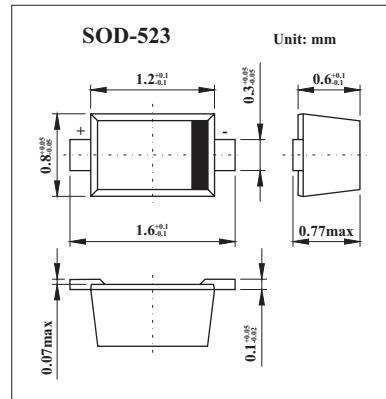


HSC276

■ Features

- High forward current, Low capacitance.
- Ultra small Flat Package (UFP) is suitable for surface mount design.



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Value	Unit
Reverse Voltage	V _R	3	V
Average rectified current	I _O	30	mA
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse voltage	V _R	I _R = 10 μA	30			V
Reverse current	I _R	V _R = 0.5 V			0.5	μA
Forward voltage	I _F	V _R = 0.5 V	35			mA
Capacitance	C	V _R = 0.5 V, f = 1 MHz			0.85	pF
ESD-Capability (Note 1)		C=200pF, Both forward and reverse direction 1 pulse.	30			V

Note

1. Failure criterion ; I_R ≥ 100mA at VR = 0.5 V

■ Marking

Marking	C2
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